



## Product Change Notification / LIAL-12WRCV778

### Date:

19-Jan-2021

### Product Category:

Memory

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 2927.001 and CCB 3280.002 Final Notice: Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

### Affected CPNs:

[LIAL-12WRCV778\\_Affected\\_CPN\\_01192021.pdf](#)  
[LIAL-12WRCV778\\_Affected\\_CPN\\_01192021.csv](#)

### Notification Text:

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of MTAI as an additional assembly and final test site for selected Atmel AT24C0xC, AT24C128C, AT24C16C, AT24C256C, AT24C32D and AT24C64D device families available in 8L SOIC package.

### Pre Change:

Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock. **or** Assembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material with NiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock. **and** Tested at ASSH or ANAP Final Test site.

**Post Change:** Assembled at ANAP assembly site using palladium coated copper (PdCu) bond wire, 8290 die attach and G700A mold compound material with NiPdAu lead plating in 60 x 60 mils paddle size without lead lock **or** Assembled at ASSH assembly site using palladium coated copper (PdCu) bond wire or palladium coated copper with gold flash (CuPdAu) bond wire, EN-4900G die attach and G700LY molding compound or CEL-9240HF10AK mold compound material with NiPdAu or Matte tin lead plating in 93 x 93 mils paddle size without lead lock **or** Assembled at MTAI assembly site using gold (Au) bond wire, 8390A die attach and G600V mold compound material with Matte tin lead plating in 90 x 90 mils paddle size with lead lock **and** Tested at ASSH, ANAP or MTAI Final Test site.

**Pre and Post Change Summary:**

|                           | Pre Change  |  |                 | Post Change                                       |  |   |
|---------------------------|---|--|-----------------|---|--|---|
| Assembly Site             | Amkor Technology Philippines (P1/P2), INC. (ANAP) | ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH) |                 | Amkor Technology Philippines (P1/P2), INC. (ANAP) | ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH) | Microchip Technology Thailand (HQ) (MTAI) |
| Wire material             | PdCu  | PdCu   | CuPdAu          | PdCu  | PdCu   | CuPdAu                                    |
| Die attach material       | 8290  | EN-4900G   |                 | 8290  | EN-4900G   |   |
| Molding compound material | G700A   | G700LY   | CEL-9240HF 10AK | G700A   | G700LY   | CEL-9240HF 10AK                           |
| Lead frame material       | CDA194  | CDA194   |                 | CDA194  | CDA194   |   |
| Paddle size               | 60 x 60 mils                                      | 93 x 93 mils   |                 | 60 x 60 mils                                      | 93 x 93 mils   |   |
| Lead Lock                 | No  | No   |                 | No  | No   |   |
| Lead Plating              | NiPdAu  | NiPdAu   | Matte tin       | NiPdAu  | NiPdAu   | Matte tin                                 |

|                              | Pre Change   |   |  | Post Change                                       |                                      |                    |
|------------------------------|--|---|--|---|--------------------------------------|--------------------|
| Final Test Site              | ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH) | Amkor Technology Philippines (P1/P2), INC. (ANAP) | ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH) | Amkor Technology Philippines (P1/P2), INC. (ANAP) | Microchip Technology Thailand (MTAI) |                    |
| Base Quantity Multiple (BQM) | Tube   | 100   | 100  | 100   | 100                                  | 100                |
|                              | Tape and Reel  | 4000  | 4000   | 4000  | 4000                                 | 4000               |
| Pin1 Orientation             | Tube   | Pin 1 side (Black)                                | Not Applicable   | Pin 1 side (Black)                                | Not Applicable                       | Pin 1 side (White) |
|                              | Tape and Reel  | Quadrant 1  | Quadrant 1   | Quadrant 1  | Quadrant 1                           | Quadrant 1         |

|  |  |
|--|--|
| Tube                                       | Minor dimensional changes – see attachment |
| Carrier Tape                               | No change                                  |
| Cover Tape                                 | Minor dimensional changes – see attachment |
| Plastic Reel                               | Minor dimensional changes – see attachment |
| Packing Procedure for Tube and Tape & Reel | See attachment                             |

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying MTAI as an additional assembly and final test site

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**February 15, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

| Workweek                  | January 2021 |    |    |    |    | February 2021 |    |    |    |    |
|---------------------------|--------------|----|----|----|----|---------------|----|----|----|----|
|                           | 01           | 02 | 03 | 04 | 05 | 06            | 07 | 08 | 09 | 10 |
| Qual Report Availability  |              |    |    | X  |    |               |    |    |    |    |
| Final PCN Issue Date      |              |    |    | X  |    |               |    |    |    |    |
| Estimated First Ship Date |              |    |    |    |    |               |    | X  |    |    |

**Method to Identify Change:** Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.PCN\_LIAL-12WRCV778\_Qual\_Report – Assembly site Qualification ReportPCN\_LIAL-12WRCV778\_Qual\_Report – Final Test site Qualification Report

**Revision History:****January 19, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_LIAL-12WRCV778\\_Pre and Post Change Summary.pdf](#)  
[PCN LIAL-12WRCV778\\_Qual Report - Assembly.pdf](#)  
[PCN LIAL-12WRCV778\\_Qual Report - Final Test.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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